Nanoveu Limited
ACN 624 421 085
Level 45, 108 St Georges Terrace
Perth WA, 6000 Australia
+61 8 6244 9095
www.nanoveu.com

ASX RELEASE **22 September 2026**

ASX: NVU

Investor Webinar Presentation

Nanoveu Limited ("Nanoveu" or the "Company") (ASX: NVU, OTCQB: NNVUF), a technology company specialising in advanced semiconductor, visualisation and materials sciences, is pleased to announce its participation at Pitt Street Research "AI and Semiconductors" webinar today.

Professor Mohamed Sabry, founder of EMASS, Nanoveu's fabless semiconductor business, will be delivering the attached presentation providing an update on the Company as well as its technology which specialises in ultra-low-power, AI-enabled system-on-chip (SoC) solutions for always-on sensing and intelligent processing.

If you would like to join, please click on the link below to register:

Date:	Tuesday, 22 September 2026
Time:	11:45am AEST / 9:45am AWST
Registration link:	https://us02web.zoom.us/webinar/register/WN_V9dcOxiKQ_GWUn7y2nrS5Q#/registration

This announcement has been authorised for release by the Board of Directors.

-ENDS-

Nanoveu Media
Alfred Chong, Nanoveu MD and CEO
P: +65 6557 0155 E: info@nanoveu.com

About Nanoveu Limited

Further details on the Company can be found at https://nanoveu.com/.

EMASS is a fabless semiconductor company specialising in ultra-low-power, AI-enabled system-on-chip (SoC) solutions for always-on sensing and intelligent processing at the edge. Its ECS-DoT architecture enables real-time AI inference at milliwatt-level power, supporting next-generation applications across drones, wearables, hearables, smart devices, industrial IoT, robotics and autonomous systems.

Spinoff is a Singapore-based aerial robotics company that designs and builds proprietary drone platforms. Its two current platforms are ALICE, a tethered aerial system engineered for high-payload, extended-duration operations with resistance to GPS and radio-frequency jamming and spoofing, and METRON, a camera-based 3D measurement system delivering millimetre-level precision with AI-driven deviation detection. Both platforms have been validated in commercial deployments with Tier-1 Singaporean customers. Spinoff Robotics provides Drone and sensing capabilities complementing the Company's ECS-DoT edge-AI silicon across defence, critical-infrastructure security and industrial inspection markets.

EyeFly3D™ is a comprehensive platform solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and the potential for integration with ultra-low-power SoC hardware.

Nanoshield™ includes protective and functional coating technologies designed for use across a range of applications, including solar and other industrial surfaces.

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PITT STREET RESEARCH

Pitt Street Research AI and Semiconductor Webinar • September 2026

Ultra-Low-Power Edge AI Semiconductors

Commercialised through EMASS

ASX: NVU | **OTCQB: NNVUF** | **nanoveu.com**

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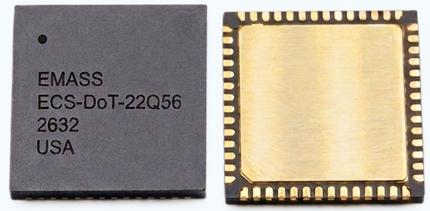
AUTHORISATION This document has been authorised for release by the Company’s Board of Directors.

Always-On AI at the Sensor Edge

EMASS builds purpose-built silicon that runs AI continuously
on battery-powered devices — the micro edge, where general-purpose chips can't



ECS-DoT 22nm Chip

< 1 mW

Always-On AI Inference

Where app processors & MCUs burn 100 mW+

< 5 ms

Inference Latency

Real-time at the sensor — no cloud or host wake

Power and latency decide whether battery-powered AI is even possible — ECS-DoT leads on both

It runs always-on inference alongside the sensor — extending battery life across:

- **Wearables**
- **Hearables**
- **Smart devices**
- **Industrial & robotics**
- **Drones**

Capital structure

ASX / OTCQB code	**NVU / NNVUF**
Previous close	**$0.055**
Market cap	**$59.80m**
Shares on issue	**1,087.3m**
Options on issue	**270.6m**
Q2 2026 cash	**$5.14m**

All figures in AUD unless stated. As at close 21 Sept 2026.

LISTING

Dual-listed in Australia (ASX) and the United States (OTCQB)

Board and Management

Alfred Chong

Group CEO & Director

- Founder of Nanoveu
- 30+ years scaling technology companies
- Former CEO — Atex Media Command (APAC), THISS Technologies, 121View
- Former CMO — 3D International

Dr. David Pevcic

Executive Chairman

- Experienced investor across resources & technology
- Non-Exec Chairman, Battery Age Minerals (ASX: BM8)
- Non-Exec Chairman, Infini Resources (ASX: I88)
- BSc, MBBS — University of Western Australia

Dr. Mohamed Sabry

CTO & Founder, EMASS

- Founder of EMASS
- Associate Professor, NTU Singapore
- Postdoc, Stanford University
- Ph.D., EPFL · Nanyang Education Award

Raymond Chen

CFO & Director

- 15+ years in corporate finance & resources
- Roles at Iluka, NRW Holdings, Equinox Resources, KPMG
- MBA, Cambridge Judge Business School

Steve Apedaile

Non-Executive Director

- 30 years' experience in accounting
- KPMG and Horwath Hong Kong
- Fellow of ICAEW · Member of AICD
- Executive Chairman, Sprintex (ASX: SIX)

EMASS Leadership

Led by veterans of the semiconductor industry

Dr. Mohamed Sabry

CTO & Founder, EMASS

- Founder of EMASS
- Associate Professor, NTU Singapore
- Postdoc, Stanford University
- Ph.D., EPFL · Nanyang Education Award

Mark Goranson

CEO, Semiconductor Technology

- VP Global Operations, TE Connectivity
- SVP Fab Operations, ON Semiconductor
- VP Fab Operations, Freescale
- Early team member, Intel

Scott Smyser

VP, Sales & Marketing

- EVP Marketing & BD, Si-Ware Systems
- VP & GM, VTI Technologies (Murata)
- SVP Sales, Atomica
- SVP Strategic Sales, Rockley Photonics

Market opportunity

A large, fast-growing edge-AI silicon market — across the five verticals EMASS targets

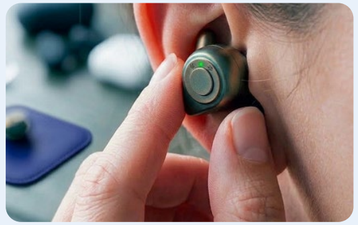
$32.4B → $102.9B

Edge-AI silicon market · 2024 to 2030

21.3%

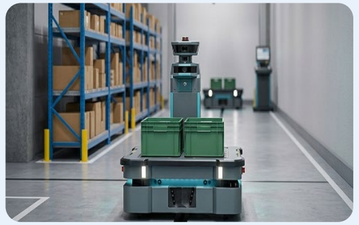
CAGR, 2024–2030

Wearables
15.4%
CAGR



Hearables
14.3%
CAGR

Smart home
5.2%
CAGR



Industrial & robotics
11.2%
CAGR

Drones
11.6%
CAGR

Edge-AI silicon market: The SHD Group, 2025. Vertical unit CAGRs (2024–2029): Frost & Sullivan. Third-party forecasts, not company guidance.

AI is Moving to the Edge — Power is the Barrier

Cloud, app processors and MCUs each break down before the always-on sensor edge

Cloud AI

Powerful, but remote

- Latency breaks real-time response
- Bandwidth and cost scale with every device
- Privacy and connectivity limit deployment

App processors & MCUs

Not built for always-on AI

- 100 mW–1 W+ just to keep AI alive
- No efficient way to watch sensors non-stop
- Battery and form factor pay the price

THE ANSWER

EMASS ECS-DoT

Architected for the sensor edge

- Sits with the sensors at sub-mW power
- Offloads always-on inference from the host
- Wakes the host only on real events
- Drops into existing designs — no redesign

ECS-DoT-22 — our current commercial chip, in customers' hands today

Up to 20× More Efficient than the Competition

Benchmarked against the leading commercially available edge-AI chips in the market

Benchmark	Metric	ECS-DoT-22	NDP120	Apollo 4
Visual Wake Words	Latency (ms)	**4.2**	12.72	N.A.
	Energy (µJ)	**3.7**	71.71	N.A.
Image Classification	Latency (ms)	**6.2**	15.98	70–160*
	Energy (µJ)	**5.5**	101.83	~2100**
Keyword Spotting	Latency (ms)	**3.9**	4.37	22–54*
	Energy (µJ)	**3.07**	31.54	~360**
Anomaly Detection	Latency (ms)	**1.2**	N.A.	2.28–5.73*
	Energy (µJ)	**0.8**	N.A.	~150**

*Source: MLCommons, 2025. *Execution time extrapolated from Ambiq comparison claims. **Numbers extracted from MLPerf Tiny benchmark report.*

CORE IMPACT

Energy per inference

Directly extends battery life or shrinks battery size

Latency

Real-time response at the sensor, no host wake-up

Drones: A New Beachhead for Micro-Edge AI

ECS-DoT with our own onboard AI models cuts drone energy use in real flight — where the competition doesn't play

Up to 51.0%

Cruise-efficiency gain in live flight

< 10 mW

Total system power for real-time optimisation

Drop-in

No changes to the drone's battery, airframe or propulsion

HOW ECS-DoT DOES IT

Sense

Reads the live flight state — speed, heading and conditions — continuously

→

Optimise

ECS-DoT + EMASS AI models find the aerodynamic optimum, onboard

→

Hold

Holds cruise speed at the optimum, cutting the speed variance that wastes energy

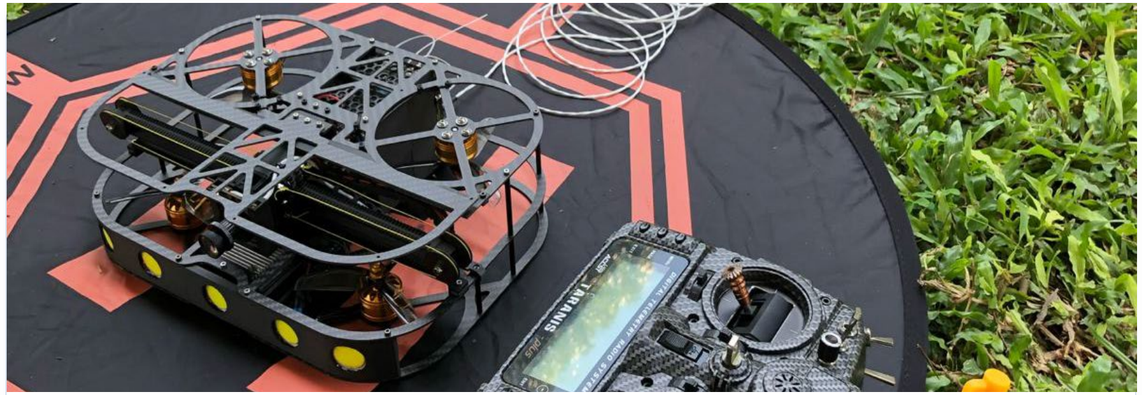
Now advancing internally with Spinoff Robotics — our acquired drone team — refining a commercial solution and building defensible IP

Two commercial drone platforms acquired through Spinoff Robotics

Both platforms validated with Tier-1 Singapore customers

ALICE

High-payload tethered drone system



METRON

Difficult to access, critical infrastructure inspection

Building on the platforms: Spinoff's airframe and engineering capability allows Nanoveu to accelerate drone edge-AI solutions with ECS-DoT, while scaling Spinoff's existing drone platforms into new industrial, maintenance and defence markets.

Years of Engineering Behind Unique Architecture

2020 — EMASS founded

2022–24 — 22 nm architecture & engineering silicon

MAR 2025 — Nanoveu acquires EMASS

H2 2025 — Commercial team buildup, samples & eval boards

JAN 2026 — 16 nm tapeout completed

H1 2026 — Best in Show ×2

H2 2026 — 22 nm full-mask fabrication

Q1 2027 — Production ramp

ECS-DoT-22 — our commercial product

- Actively engaging customers for design-ins
- Ramping to production in Q1 2027

ECS-DoT-16 — next-gen, already taped out

- Next-gen silicon, taped out ahead of the competition
- Built to keep our lead

ECS-DoT 22nm Target Applications Under Active Evaluation

Target applications across edge AI progressing to design-in

Smart ring

On-device health, motion and gesture inference in the tightest wearable power and form-factor envelope.

Tablet platform

Always-on audio, vision and sensor input.

Hearables

Local keyword spotting and motion-triggered wake-up with sub-10 ms on-device response.

Dash & smart cams

Real-time on-device object and event detection, kept local within the camera's power limits.

Predictive maintenance

On-device vibration and acoustic anomaly detection for always-on industrial monitoring.

Sample asset tracking module

Asset tracking

Always-on location and condition sensing for cold-chain and logistics assets, at sub-milliwatt power.

Developing a Partner Ecosystem to Extend Our Reach

Strategic partners and reference designs extending our reach, credibility and visibility

Global technology distributor & engineering partner

Co-developed a predictive-maintenance reference design

Global semiconductor provider

ECS-DoT-22 + LoRaWAN — predictive maintenance & audio-security demos

Leading semiconductor & sensor provider

Jaw-motion sensing for bone-conduction audio in hearables & AR glasses

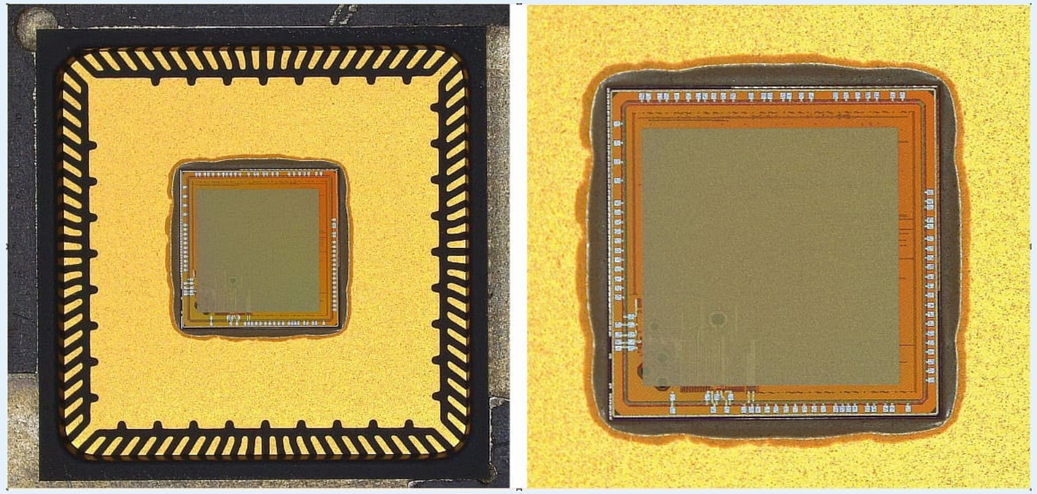
World-leading MEMS sensor provider

Multi-sensor asset-tracking reference design

ECS-DoT-16 Milestone: First engineered samples back from TSMC

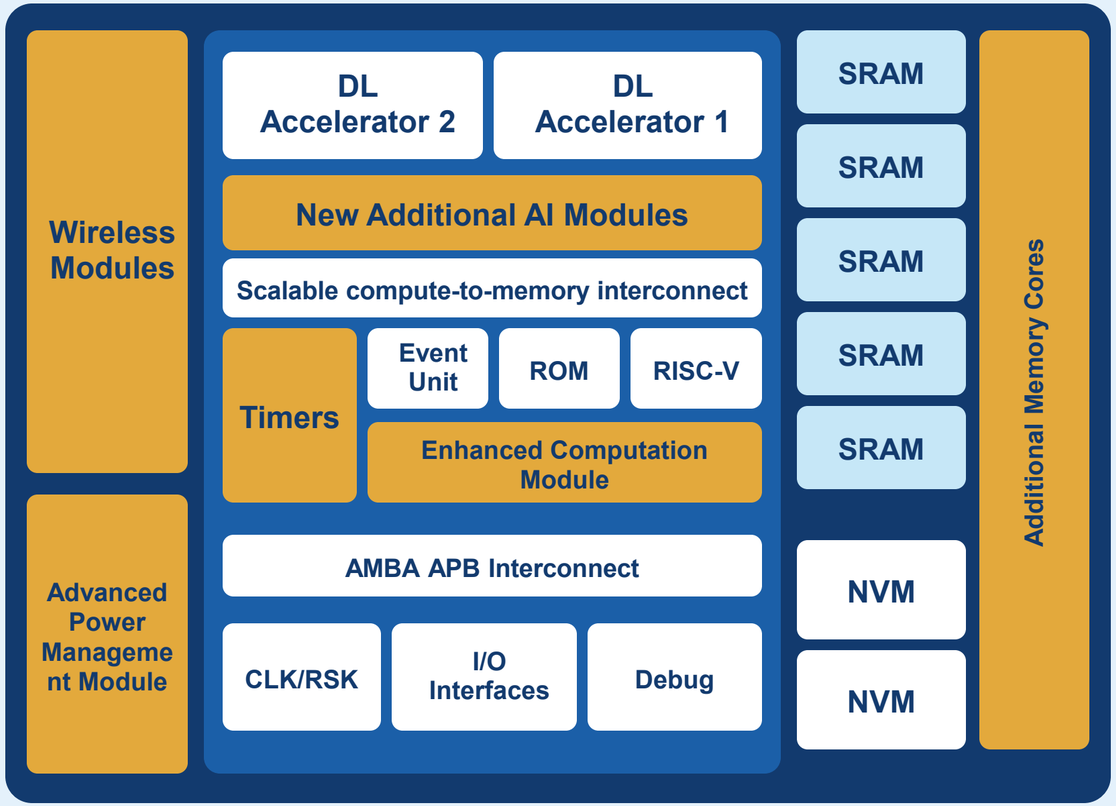
First packaged silicon of the 16 nm ECS-DoT (left) and the improved architecture with new AI, wireless and power modules (right)

ENGINEERED SAMPLES OF ECS-DOT-16



Actual engineered samples of ECS-DoT-16, fabricated at 16 nm. Packaged die and bare die close-up.

16 NM CHIP ARCHITECTURE



Key new features with ECS-DoT-16

New features enabled by our 16nm node size

Integrated Bluetooth Low Energy subsystem

Full BLE signal chain on-chip. Removes the separate wireless chip, lowering customer cost and opening up more applications.

Expanded on-chip SRAM

More on-chip memory runs larger AI models locally, supporting higher-value vision and multi-sensor products while cutting energy use.

Adaptive fine-grained power-management fabric

Microsecond sleep and wake with power and clock gating. Extends battery life for always-on devices.

Dedicated AI acceleration module for object detection

Purpose-built engine for YOLO-Nano, MobileNet-SSD and FOMO-style detectors. Delivers real-time detection at the edge without cloud costs or added hardware.

Hardware floating-point unit

A first for ECS-DoT, supporting FP16 and FP32. Customers can port existing code and libraries directly, shortening development time and speeding time to market

CARRIED OVER

Full software and workflow compatibility with the 22 nm ECS-DoT is maintained across all of the above.

Positioned to Lead Micro-Edge AI

A large, fast-growing market

$32B → $103B edge-AI silicon market by 2030.

Benchmark-leading efficiency

20× more efficient than the competition.

A commercial chip today

ECS-DoT-22 in customers' hands with active design-ins; production targeted Q1 2027.

Next-gen already taped out

ECS-DoT-16 taped out — staying ahead of the competition.

A growing partner ecosystem

Reference designs with Arrow, Semtech, ST and Bosch.

A new drone beachhead

Up to 51% live-flight efficiency gains — where no competitor plays.

Thank you

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